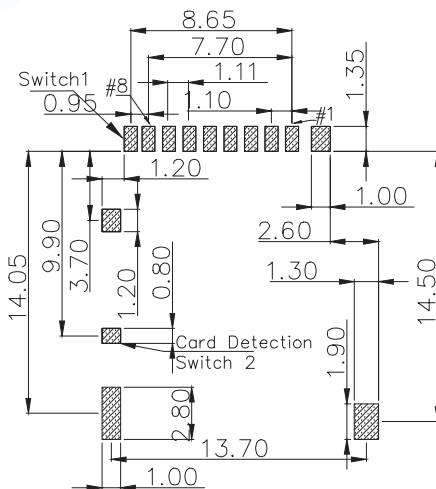
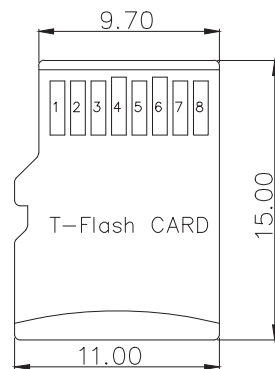
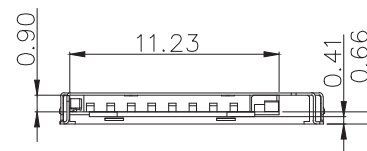
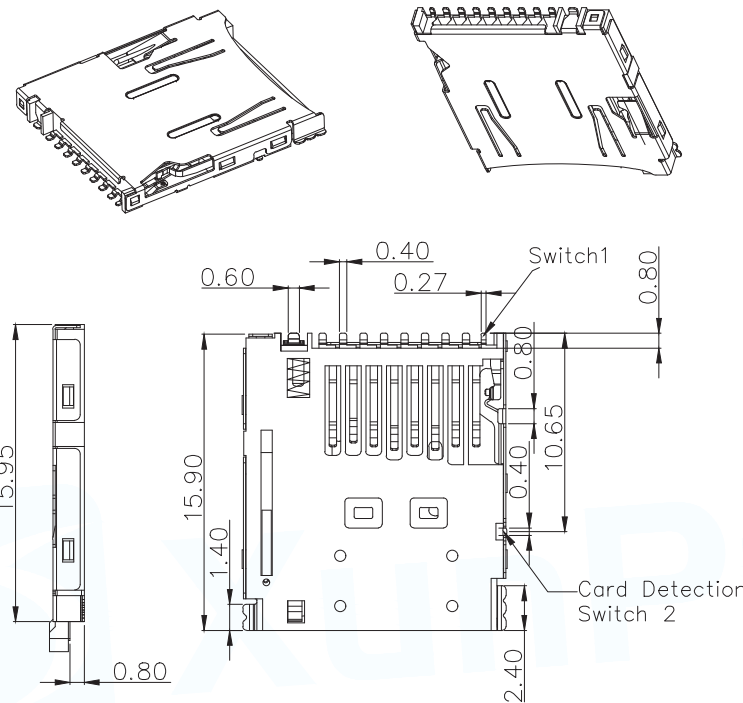
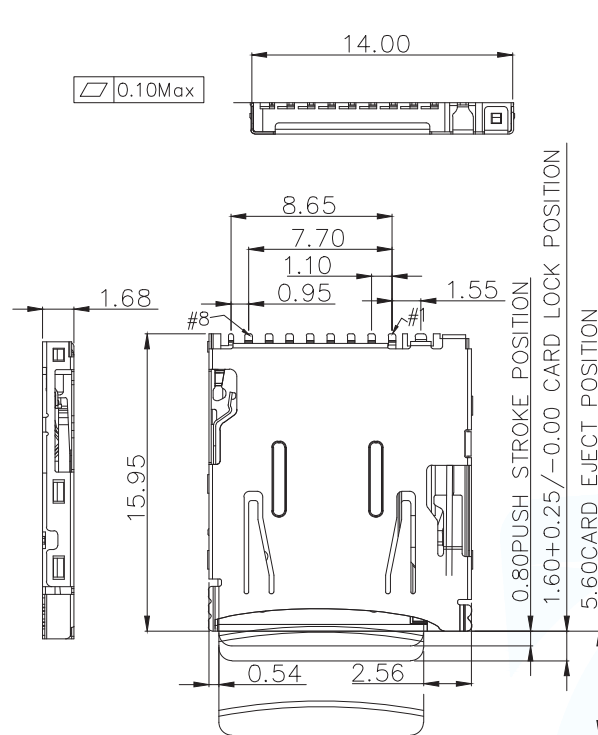
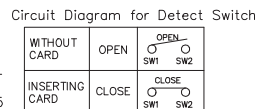




■ PAD AREA
■ KEEP OUT AREA

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05



SPECIFICATION

MATERIAL:

INSULATOR: HIGH TEMPERATURE

THERMOPLASTIC, UL 94V-0.

CONTACT: COPPER ALLOY

SHELL: SUS

PLATING:

CONTACT: PLATED 50U" NI ALL, OVER ALL
AU 1U

SHELL: PLATED 50U" NI OVERALL

PLATED 1U" AU SELECTIVE CONTACT AREA

ELECTRICAL:

CURRENT RATING : 0.5A.MAX

VOLTAGE RATING : 5V AC/DC

AMBIENT TEMPERATURE RANGE : $-25^{\circ}\text{C} \sim +85^{\circ}\text{C}$ STORAGE TEMPERATURE RANGE : $-25^{\circ}\text{C} \sim +85^{\circ}\text{C}$

AMBIENT HUMIDITY RANGE : 95% R.H. MAX.

CONTACT RESISTANCE: 100M MAX.

INSULATION RESISTANCE: 1000M MIN./500VDC

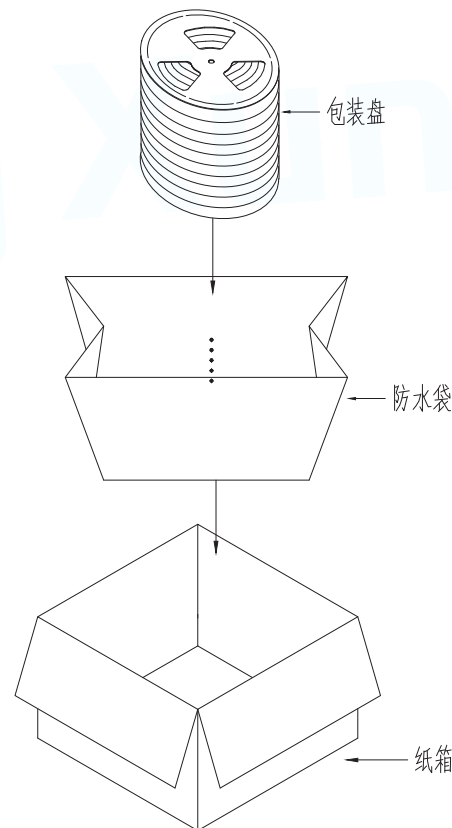
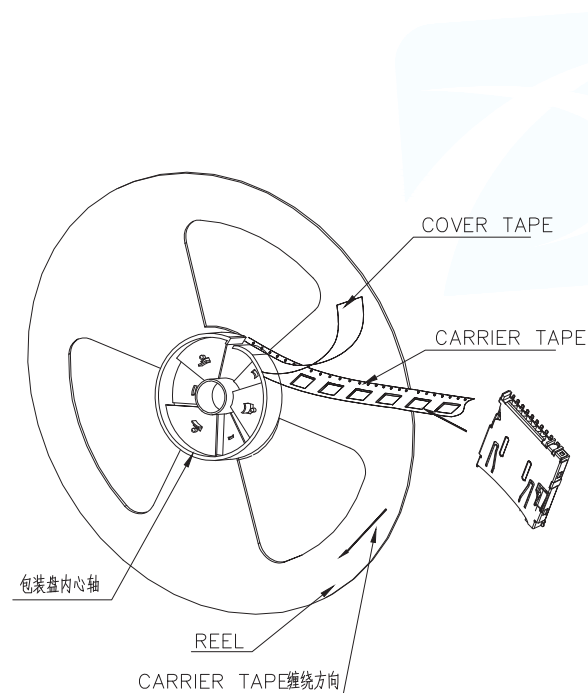
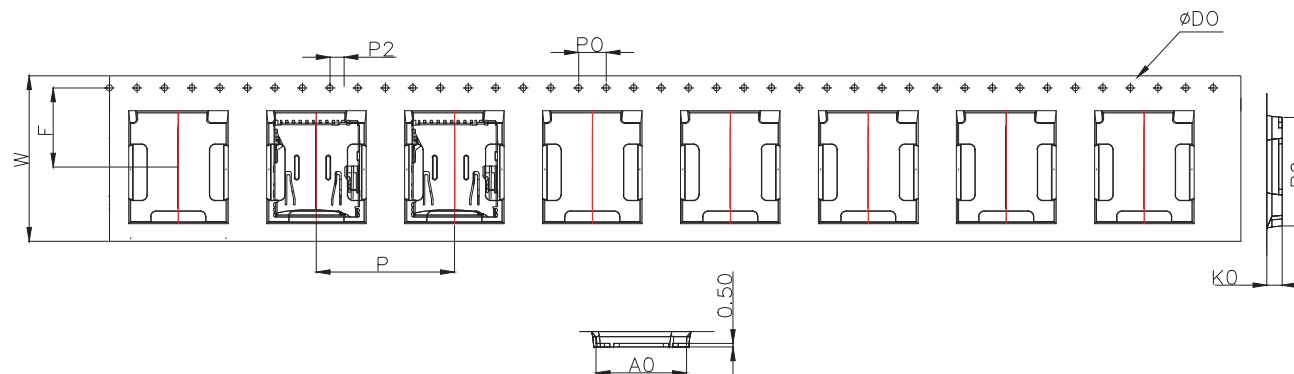
REFLOW PEAK TEMP: 260°C

MATING CYCLES: 5,000 INSERTIONS

TF CARD PIN DEFINE

PIN NO.	NAME	YTYPE	DESCRIPTION
1	DAT2	I/O/PP	DATE LINE(BIT2)
2	CD/DAT3	I/O/PP	CARD DETECT DATE LIN(BIT3)
3	CMD	PP	COMMAND RESPONSE
4	VDD	S	SUPPLY VOLTAGE
5	CLX	I	CLOCK
6	VSS	S	SUPPLY VOLTAGE GROUND
7	DAT0	I/O/PP	DATE LINE(BIT0)
8	DAT1	I/O/PP	DATE LINE(DIT1)

MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES		TITLE: Micro SD Card Push Push and CD Pin H1.68	
DECIMALS:	ANGLES: $\pm 1^{\circ}$	PAR	TF-111-ARP10
X.X: ± 0.15		DWN	
X.XX: ± 0.10		CHKD	
X.XXX: ± 0.05		APVD	
CUSTOMER COPY		SCALE: 1:1	UNIT: MM
		SIZE: A4	SHEET: 1F1
			REV: A



一:

1. 将成品一一放入包装盘内, 依同一方向放入
2. 包装时, 如图所示.

3. 一个包装然放置1000个成品

二:

1. 一只纸箱可放置5个包装盘
2. 一只纸箱可放5000PCS的成品
3. 将成品放入包装盘内包装完后再装箱

产品单重: 0.70g

每盘单重: 920g

纸箱规格: 350*350*165

MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co., Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: Micro SD Card Push Push and CD Pin H1.68 包装
DECIMALS:	ANGLES: $\pm 1^\circ$		PAR TF-111-ARP10
X.X: ± 0.15			DWN
X.XX: ± 0.10			CHKD
X.XXX: ± 0.05			APVD
CUSTOMER COPY		SCALE: 1:1	UNIT: MM
		SIZE: A4	SHEET: 1F1
			REV: A